

SEMICONDUCTOR STRUCTURE AND METHOD FOR MANUFACTURING SEMICONDUCTOR STRUCTURE

ABSTRACT

The present disclosure relates to the technical field of semiconductors, and provides a semiconductor structure and a method for manufacturing a semiconductor structure. The semiconductor structure comprises a first chip and a second chip, a first electrically conductive connection line of the first chip being connected to a first electrically conductive contact pad, a second electrically conductive connection line of the second chip being connected to a second electrically conductive contact pad, the first electrically conductive contact pad comprising a first electrical conductor and a second electrical conductor, and the second conductive contact pad comprising a third electrical conductor and a fourth electrical conductor. By means of causing the first electrical conductor to be directly opposite the fourth electrical conductor, and the second electrical conductor to be directly opposite the third electrical conductor, the first electrically conductive contact pad and the second electrically conductive contact pad can be connected in advance, and the pre-connected first chip and second chip then transferred to be bonded. Since pre-connection of the first chip and the second chip is completed before transfer, relative movement of the first chip and the second chip does not occur, ensuring subsequent reliable alignment of the first chip and the second chip, and improving performance of the semiconductor structure.

[Fig. 1]